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Printed boards - Part 20: Printed circuit boards for high-brightness LEDs

Táto norma obsahuje anglickú verziu európskej normy.  
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 09/16

Obsahuje: EN 62326-20:2016, IEC 62326-20:2016

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Podľa zákona č. 264/1999 Z. z. v znení neskorších predpisov sa môžu slovenské technické normy rozmnožovať a rozširovať iba so súhlasom Úradu pre normalizáciu, metrológiu a skúšobníctvo SR.

EUROPEAN STANDARD

**EN 62326-20**

NORME EUROPÉENNE

EUROPÄISCHE NORM

May 2016

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English Version

Printed boards - Part 20: Printed circuit boards for high-brightness LEDs  
(IEC 62326-20:2016)

Cartes imprimées - Partie 20: Cartes de circuits imprimés destinées aux LED à haute luminosité  
(IEC 62326-20:2016)

Leiterplatten - Teil 20: Elektronische Leiterplatte für Hochleistungs-LEDs  
(IEC 62326-20:2016)

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Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels**

**European foreword**

The text of document 91/1311/FDIS, future edition 1 of IEC 62326-20, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62326-20:2016.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2016-12-09
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2019-03-09

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-1	NOTE	Harmonized as EN 60068-1.
IEC 60068-2-1	NOTE	Harmonized as EN 60068-2-1.
IEC 60068-2-2	NOTE	Harmonized as EN 60068-2-2.
IEC 60068-2-6	NOTE	Harmonized as EN 60068-2-6.
IEC 60068-2-20	NOTE	Harmonized as EN 60068-2-20.
IEC 60068-2-21	NOTE	Harmonized as EN 60068-2-21.
IEC 60068-2-30	NOTE	Harmonized as EN 60068-2-30.
IEC 60068-2-38	NOTE	Harmonized as EN 60068-2-38.
IEC 60068-2-53	NOTE	Harmonized as EN 60068-2-53.
IEC 60068-2-58	NOTE	Harmonized as EN 60068-2-58.
IEC 60068-2-64	NOTE	Harmonized as EN 60068-2-64.
IEC 60068-2-66	NOTE	Harmonized as EN 60068-2-66.
IEC 60068-2-78	NOTE	Harmonized as EN 60068-2-78.
IEC 60068-2-80	NOTE	Harmonized as EN 60068-2-80.
IEC 61189-1	NOTE	Harmonized as EN 61189-1.

IEC 61189-2	NOTE	Harmonized as EN 61189-2.
IEC 61189-11	NOTE	Harmonized as EN 61189-11.
IEC 61189-3-913	NOTE	Harmonized as EN 61189-3-913.
IEC 61190-1-1	NOTE	Harmonized as EN 61190-1-1.
IEC 61190-1-2	NOTE	Harmonized as EN 61190-1-2.
IEC 61190-1-3	NOTE	Harmonized as EN 61190-1-3.
IEC 61249-2-8	NOTE	Harmonized as EN 61249-2-8.
IEC 62137-1-3	NOTE	Harmonized as EN 62137-1-3.
IEC 62137-1-4	NOTE	Harmonized as EN 62137-1-4.
IEC 62326-1	NOTE	Harmonized as EN 62326-1.
IEC 62326-4	NOTE	Harmonized as EN 62326-4.
ISO 291	NOTE	Harmonized as EN ISO 291.
ISO 2409	NOTE	Harmonized as EN ISO 2409.
ISO 3599	NOTE	Harmonized as EN ISO 3599.
ISO 3611	NOTE	Harmonized as EN ISO 3611.
ISO 4957	NOTE	Harmonized as EN ISO 4957.
ISO 291	NOTE	Harmonized as EN ISO 291.
ISO 6906	NOTE	Harmonized as EN ISO 6906.
ISO 8512-1	NOTE	Harmonized as EN ISO 8512-1.
ISO 8512-2	NOTE	Harmonized as EN ISO 8512-2.
ISO 9445-1	NOTE	Harmonized as EN ISO 9445-1.
ISO 9453	NOTE	Harmonized as EN ISO 9453.
ISO 9454-1	NOTE	Harmonized as EN ISO 9454-1.
ISO 9455 (series)	NOTE	Harmonized as EN ISO 9455 (series).
ISO 13385-1	NOTE	Harmonized as EN ISO 13385-1.
ISO 15184	NOTE	Harmonized as EN ISO 15184.

## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	-
IEC 61189-3	2007	Test methods for electrical materials, printed boards and other interconnection structures and assemblies -- Part 3: Test methods for interconnection structures (printed boards)	EN 61189-3	2008
IEC 61249-2-6	-	Materials for printed boards and other interconnecting structures -- Part 2-6: Reinforced base materials, clad and unclad - Brominated epoxide non-woven/woven E-glass reinforced laminated sheets of defined flammability (vertical burning test), copper-clad	EN 61249-2-6	-
IEC 61249-2-7	-	Materials for printed boards and other interconnecting structures -- Part 2-7: Reinforced base materials, clad and unclad - Epoxide woven E-glass laminated sheet of defined flammability (vertical burning test), copper-clad	EN 61249-2-7	-
IEC 62878-1-1	-	Device embedded substrate - Generic specification - Test method	EN 62878-1-1	-



# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



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**Printed boards –  
Part 20: Printed circuit boards for high-brightness LEDs**

**Cartes imprimées –  
Partie 20: Cartes de circuits imprimés destinées aux LED à haute luminosité**





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# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



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**Printed boards –  
Part 20: Printed circuit boards for high-brightness LEDs**

**Cartes imprimées –  
Partie 20: Cartes de circuits imprimés destinées aux LED à haute luminosité**

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## CONTENTS

FOREWORD.....	6
1 Scope.....	8
2 Normative references.....	8
3 Terms, definitions and abbreviations .....	8
3.1 Terms and definitions .....	8
3.2 Abbreviations .....	8
4 Classification and class of the printed circuit board for high-brightness LEDs.....	9
5 Design rules and allowance .....	10
5.1 Panel and board sizes .....	10
5.1.1 Board size .....	10
5.1.2 Allowance of dimensions .....	11
5.1.3 Perforation and slit.....	11
5.1.4 V-cut.....	12
5.2 Total board thickness .....	13
5.3 Holes.....	14
5.3.1 Insertion holes and vias .....	14
5.3.2 Datum hole .....	16
5.3.3 Assembly hole (a through-hole without wall plating) .....	16
5.4 Conductor .....	17
5.4.1 Width of conductor pattern and its allowance .....	17
5.4.2 Distance between conductors and its allowance.....	17
5.4.3 Thickness of the insulating layer.....	18
5.5 Printed contact.....	18
5.5.1 Allowance of the distance between the centers of two adjacent printed contacts.....	18
5.5.2 Allowance of the terminal width of printed contacts .....	19
5.5.3 Shift of the center of printed contacts on front and back sides of a board.....	19
5.6 Land pattern .....	20
5.6.1 Allowance of the distance between the centers of two lands.....	20
5.6.2 Allowance of the width of a land .....	20
5.6.3 Land diameter and its allowance for BGA/CSP.....	21
5.7 Fiducial mark and mark for component positioning .....	22
5.7.1 Typical form and size of the fiducial mark .....	22
5.7.2 Dimensional allowance of fiducial mark and component positioning mark .....	23
5.7.3 Position allowance of the component positioning mark .....	23
5.8 Interlayer connection – Copper plating.....	23
6 Quality .....	24
6.1 Gap between conductor and the wall of a component insertion hole or a via .....	24
6.2 Positional deviation between conductor layers of a multilayer board .....	24
6.3 Minimum land width.....	24
6.4 Surface treatment .....	25
6.4.1 Gold plating for printed contact.....	25
6.4.2 Other surface treatment .....	26
6.5 Defects of solder resist.....	26
6.6 Symbol mark.....	28
6.6.1 General .....	28

6.6.2	Conductor surface.....	28
6.6.3	Between conductors.....	28
6.6.4	Defects within insulating layers .....	29
6.6.5	Routing and drilling .....	30
6.6.6	Conductor pattern .....	30
6.7	Land .....	30
6.8	Land of a land pattern .....	31
6.9	Defects in a land for BGA/CSP mounting .....	32
6.10	Printed contact.....	32
7	Performance and test methods.....	34
7.1	Resistance of conductors .....	34
7.2	Current proof of conductor and plated through hole.....	35
7.3	Observation of component mountings and vias .....	36
7.3.1	Observation with standard conditions .....	36
7.3.2	Observation after thermal shock test .....	38
8	Marking, packaging and storage.....	39
8.1	Marking on a product.....	39
8.2	Marking on the package .....	39
8.3	Packaging and storage.....	40
8.3.1	Packaging.....	40
8.3.2	Storage.....	40
	Annex A (informative) Classification and class of the PCB for high-brightness LEDs.....	41
	Bibliography .....	46
	Figure 1 – Example of a classification and its application.....	10
	Figure 2 – Board arrangement in a panel.....	11
	Figure 3 – Distances from the datum point to perforation and slit .....	12
	Figure 4 – Distance from the datum point to the V-cut.....	12
	Figure 5 – Allowance of position off-set of V-cuts on front and back surfaces .....	13
	Figure 6 – PWB board with symbol mark, solder resist, copper foil and plating .....	13
	Figure 7 – Positions of component insertion holes .....	15
	Figure 8 – Distance between the wall of a hole and the board edge .....	15
	Figure 9 – Wall of a hole and the minimum designed spacing to the inner conductor .....	16
	Figure 10 – Width of finished conductor.....	17
	Figure 11 – Distance between conductor and board edge .....	18
	Figure 12 – Thickness of the insulating layer .....	18
	Figure 13 – Distance between centers of terminals of printed contacts .....	19
	Figure 14 – Terminal width of a printed contact .....	19
	Figure 15 – Shift of the center of printed contacts on front and back sides of a board .....	20
	Figure 16 – Land pattern.....	20
	Figure 17 – Land width of a land pattern.....	21
	Figure 18 – Land diameter of BGA/CSP formed of a conductor only.....	21
	Figure 19 – Land diameter ( <i>d</i> ) of BGA/CSP formed at the opening of solder resist.....	22
	Figure 20 – Examples of fiducial mark and component positioning mark.....	23
	Figure 21 – Minimum land width.....	25

Figure 22 – Exposure of conductor.....	26
Figure 23 – Minimum land with caused by the shift of solder resist.....	27
Figure 24 – Overlap, smear and shift of solder resist .....	27
Figure 25 – Examples of smear or blur .....	28
Figure 26 – Example of measling .....	29
Figure 27 – Examples of crazing .....	29
Figure 28 – Conductor nicks.....	30
Figure 29 – Conductor residue .....	30
Figure 30 – Land .....	31
Figure 31 – Defects in a land of a land pattern.....	31
Figure 32 – Defects in BGA/CSP mounting lands.....	32
Figure 33 – Areas to be checked for defects of a printed contact.....	33
Figure 34 – Defects in a printed contact .....	33
Figure 35 – Relations between resistance and width, thickness and temperature of a conductor .....	35
Figure 36 – Relationship between current, conductor width and thickness and temperature rise .....	36
Figure 37 – Defect on a plating of a component hole .....	37
Figure 38 – Resin smear .....	38
Figure 39 – Corner crack .....	38
Figure 40 – Barrel crack.....	39
Figure 41 – Foil crack .....	39
Figure A.1 – Relation between thermal conductive parameter and heat transfer coefficient parameter .....	42
Table 1 – Application and classification .....	9
Table 2 – Panel dimensions .....	11
Table 3 – Allowance of dimensions .....	11
Table 4 – Allowance of the distances from the datum point to perforation and slit.....	12
Table 5 – Allowance of the distance from the datum point to the center of the V-cut .....	13
Table 6 – Total thickness and its allowance .....	14
Table 7 – Allowance of holes for component insertion.....	14
Table 8 – Position allowance of component insertion holes .....	15
Table 9 – Distance between the wall of a hole and board edge .....	16
Table 10 – Minimum clearance between the wall of a hole and the inner layer conductor .....	16
Table 11 – Allowance of conductor width .....	17
Table 12 – Allowance of the distance between conductors .....	18
Table 13 – Allowance of terminal width of a printed contact .....	19
Table 14 – Allowance of terminal width of a printed contact .....	20
Table 15 – Allowance of the width of a land of a land pattern .....	21
Table 16 – Land diameter and its allowance for BGA/CSP .....	22
Table 17 – Allowance of the land diameter ( $d$ ) of BGA/CSP formed at the opening of solder resist.....	22

Table 18 – Shapes and sizes of typical fiducial marks and component positioning marks .....	23
Table 19 – Minimum thickness of copper plating .....	23
Table 20 – Minimum thickness of copper plating .....	24
Table 21 – Minimum land width .....	27
Table 22 – Overlap, smear and shift of solder resist over a fool print.....	28
Table 23 – Allowance of the area of a defect, remaining width and protrusion of a land .....	31
Table 24 – Defect of a land of a land pattern .....	32
Table 25 – Defects in BGA/CSP mounting lands .....	32
Table 26 – Defects in a printed contact .....	34
Table 27 – Specification and test methods of resistance of conductors.....	34
Table 28 – Specification and test methods of current proof .....	35
Table 29 – Allowance in horizontal sectioning.....	38
Table A.1 – Relation between thermal conductive parameter and heat transfer coefficient parameter .....	42
Table A.2 – Related test methods.....	43

# INTERNATIONAL ELECTROTECHNICAL COMMISSION

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## PRINTED BOARDS –

### Part 20: Printed circuit boards for high-brightness LEDs

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International Standard IEC 62326-20 has been prepared by IEC technical committee 91: Electronics assembly technology.

This first edition cancels and replaces the IEC/PAS 62326-20 published in 2011, and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) this edition focuses on the technical content of the printed circuit board for high-brightness LEDs;
- b) the figures related to the printed circuit board for high-brightness LEDs have been refined.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1311/FDIS	91/1330/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

A list of all parts in the IEC 62326 series, published under the general title *Printed boards*, can be found on the IEC website.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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## PRINTED BOARDS –

### Part 20: Printed circuit boards for high-brightness LEDs

#### 1 Scope

This part of IEC 62326 specifies the properties of the printed circuit board (hereafter described as PCB) for high-brightness LEDs. Many aspects of the PCB for high-brightness LEDs are identical with those of ordinary PCBs, therefore, some aspects of this standard also describe general aspects.

#### 2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61189-3:2007, *Test methods for electrical materials, printed boards and other interconnection structures and assemblies – Part 3: Test methods for interconnection structures (printed boards)*

IEC 61249-2-6, *Materials for printed boards and other interconnecting structures – Part 2-6: Reinforced base materials, clad and unclad – Brominated epoxide non-woven/woven E-glass reinforced laminated sheets of defined flammability (vertical burning test), copper-clad*

IEC 61249-2-7, *Materials for printed boards and other interconnecting structures – Part 2-7: Reinforced base materials clad and unclad – Epoxide woven E-glass laminated sheet of defined flammability (vertical burning test), copper-clad*

IEC 62878-1-1, *Device embedded substrate – Part 1-1: Generic specification – Test methods*

**koniec náhľadu – text ďalej pokračuje v platenej verzii STN**